

QUANTUM PHOTONIC PROJECTS

- QUEST: Design and Packaging of a Compact Entangled-Photon Source for Space Quantum Key Distribution
 - Packaged for real-world applicationsTarget space applications
 - > Telecoms and space-qualified processes to ensure stability and reliability



- Single Ion Microfabricated ion trap, coupled with scalable entanglement techniques facilitate advances in atomic clocks and quantum processors
 - Design and manufacture of a bespoke ITCC (Ion-Trap-Chip-Carrier) to hold a double sided MEMS silicon chip
 - Bespoke and scalable assembly processes
 - Withstands UHV application requirements

- SLAM: Vacuum package with fibre optic access & SPADs, with integrated Michelson interferometer to measure a MEMS gravimeter
 - > multi-stage TEC < -60 °C
 > High vacuum sealed, fibre coupled
 > Low temperature cold weld crimp sealing processes



- rAmpart: fibre-coupled tapered amplifier for Quantum applications
 - »Automated wirebonding, Pick & Place
 - »High fibre coupling efficiency
 - >SPAD assisted time-of-flight imaging
 - Transferable technology: Quantum cooling, LiDAR applications

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